



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-10-28
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U585RIT3Q	795W*482XXU	A	998Z	2024-10-28
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	363	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	10x10	64	Gull wing	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration :							Mfr Item Name	795W*482XXU		363.2690		600000.0	100000.0	
note : Substance present with less 0.001mg will not be declared in this document														
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)		
Die or dies	M-011 Other inorganic materials	14.654	mg	supplier	die	Silicon (Si)	7440-21-3		14.083	mg	961035	38767		
				supplier	metallization	Aluminium (Al)	7429-90-5		0.063	mg	4299	173		
				supplier	metallization	Copper (Cu)	7440-50-8		0.188	mg	12829	518		
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	68	3		
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.032	mg	2184	88		
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	546	22		
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	68	3		
				supplier	Passivation	Silicon Nitride	12033-89-5		0.045	mg	3071	124		
				supplier	Passivation	Silicon Oxide	7631-86-9		0.233	mg	15900	641		
				supplier	Metals	Silver	7440-22-4		1.624	mg	815000	4471		
Glue epoxy (3230)	M-011 Other inorganic materials	1.993	mg	supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))bisox	39817-09-9		0.060	mg	30000	165		
				supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.060	mg	30000	165		
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.060	mg	30000	165		
				supplier	Organic Compounds	Dodecylloxirane	3234-28-4		0.060	mg	30000	165		
				SVHC	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.060	mg	30000	165		
				supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.060	mg	30000	165		
				supplier	Metallic compounds	Copper oxide	1317-38-0		0.010	mg	5000	27		
				supplier	Plastics/polymers	Epoxy Resin A	Proprietary		5.057	mg	21000	13921		
Encapsulation (EME-G631SHQ)	M-011 Other inorganic materials	240.805	mg	supplier	Plastics/polymers	Epoxy Resin B	Proprietary		5.057	mg	21000	13921		
				supplier	Plastics/polymers	Phenol Resin	Proprietary		13.485	mg	56000	37121		
				supplier	Glass	Silica(Amorphous)A	60676-86-0		187.936	mg	780450	517347		
				supplier	Glass	Silica(Amorphous)B	7631-86-9		27.770	mg	115320	76445		
				supplier	Non-metals	Carbon Black	1333-86-4		1.500	mg	6230	4129		
				supplier	Metals	Gold	7440-57-5		1.079	mg	1000000	2970		
Wire (Au)	Bonding Wire	1.079	mg	supplier	Metals	Tin	7440-31-5		1.438	mg	1000000	3958		
Plating Anode (Pure Tin)	M-011 Other inorganic materials	1.438	mg	supplier	Metals	Copper	7440-50-8		100.428	mg	972200	276456		
Leadframe (C194+Ag)	Copper & its alloys	103.300	mg	supplier	Metals	Iron	7439-89-6		2.366	mg	22900	6513		
				supplier	Metals	Zinc	7440-66-6		0.155	mg	1500	427		
				supplier	Non-Metals	Phosphorus	7723-14-0		0.031	mg	300	85		
				supplier	Metals	Silver	7440-22-4		0.320	mg	3100	881		